

- x Qualified for Automotive Applications
 - x AEC-Q100 Qualified with the Following Results:
 - Device Temperature Grade 1: -40°C to 125°C Ambient Operating Temperature Range
 - Device HBM ESD Classification Level H2
 - Device CDM ESD Classification Level C3B
 - x Wide Input Voltage Range: 3.2V-50V
 - x Low Shutdown Current 3.7μA
 - x Low Quiescent operating Current: 450μA
 - x Adjustable Switching Frequency: 100KHz to 2.2MHz
 - x Integrated Frequency Dithering for EMI Mitigation
 - x External Frequency Synchronic
 - x External Compensation
 - x Supports additional Slope Compensation
 - x 22ms Internal Soft-start Time
 - x Integrated Protection Feature
 - Constant Peak-Current Protection Threshold Over Input Voltage
 - Output Overvoltage Protection
 - Adjust Under-Voltage Lockout
 - Constant Current Overload Protection
 - Thermal Shutdown Protection:165°C
 - x MSOP-8L(3mm*3mm) Package
-
- x Muti-output Flyback
 - x LED Bias Supply
 - x Portable Speaker Supply
 - x Battery Powered Boost/Flyback/SEPIC application

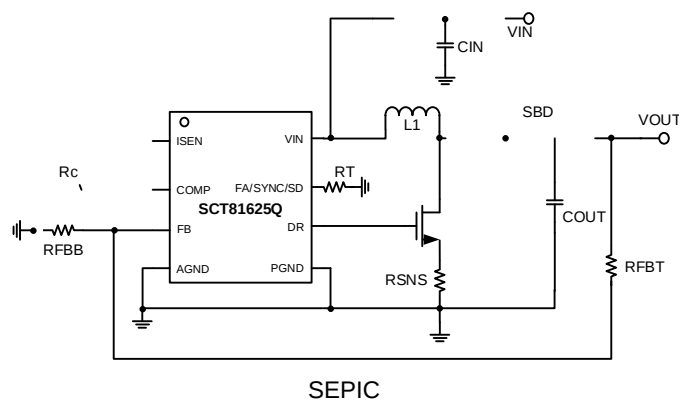
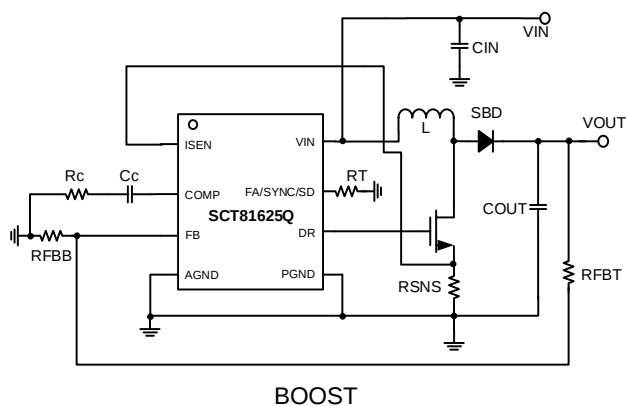
The SCT81625Q device is a wide input, non-synchronous boost controller. The Device can be used in Boost, SEPIC and Flyback converters and topologies.

The switching frequency of the SCT81625Q device can be adjusted to any value between 100kHz and 2.2MHz by using a single external resistor or by synchronizing it to an external clock. Current mode control provides superior bandwidth and transient response in addition to cycle-by-cycle current limiting. Current limit is adjustable through an external resistor.

The SCT81625Q is an Electromagnetic Interference (EMI) friendly controller with implementing optimized design for EMI reduction. The SCT81625Q features Frequency Spread Spectrum (FSS) with $\pm 6\%$ jittering span of the switching frequency and modulation rate 1/512 of switching frequency to reduce the conducted EMI.

The SCT81625Q device has built-in protection features such as thermal shutdown, short-circuit protection and overvoltage protection. Power-saving shutdown mode reduces the total supply current to 3.7μA. Integrated current slope compensation simplifies the design and, if needed for specific applications, can be increased using a single resistor.

The device is available in a MSOP-8L(3mm*3mm) Package.



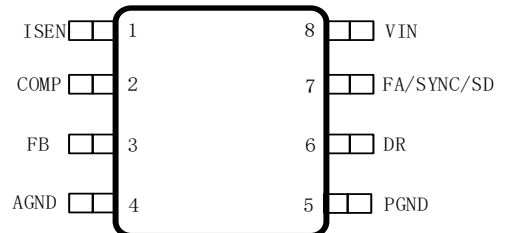
SCT81625Q

E6+ARXV_f SVα WcadVgZfd dVgZ_d Rj UZWcW aRXV_f SVα Z_eV Tf αV_egVαZ_
CVgZ_d +CVVRdVUe > Rc Ve

PART NUMBER	PACKAGING TYPE	STANDARD PACK QTY	PACKAGE MARKING	PINS	PACKAGE DESCRIPTION
SCT81625QMTDR	Tape & Reel	4000	1625Q	8	8-Lead 3mm×3mm Plastic MSOP

Over operating free-air temperature unless otherwise noted⁽¹⁾

DESCRIPTION	MIN	MAX	UNIT
VIN	-0.3	62	V
DR	-1	6.6	V
ISEN, COMP, FB, FA/SYNC/SD	-5	5.5	V
Peak Driver Output Current		1 ⁽²⁾	A
Junction temperature ⁽²⁾	-40	150	°C
Storage temperature T _{STG}	-65	150	°C



Top View: 8-Lead Plastic MSOP 3mmx3mm

- (1) Stresses beyond those listed under Absolute Maximum Rating may cause device permanent damage. The device is not guaranteed to function outside of its Recommended Operation Conditions.
- (2) Guaranteed by design, not tested in productions.
- (3) The IC includes over temperature protection to protect the device during overload conditions. Junction temperature will exceed 170°C when over temperature protection is active. Continuous operation above the specified maximum operating junction temperature will reduce lifetime.

NAME	NO.	DESCRIPTION
ISEN	1	Current sense input pin. Connect to the positive side of the current sense resistor through a short path.
COMP	2	Output of the internal transconductance error amplifier. Connect the loop compensation components between this pin and GND.
FB	3	Inverting input of the error amplifier. Connect a voltage divider from the output to this pin to set output voltage. The device regulates FB voltage to the internal reference value of 1.26V typical.
AGND	4	Analog ground pin.
PGND	5	Power ground pin.
DR	6	N-channel MOSFET gate drive output. Connect directly to the gate of the N-channel MOSFET through a short, low inductance path.
FA/SYNC/SD	7	Switching frequency setting pin. The switching frequency is programmed by a single resistor between this pin and AGND. The internal clock can be synchronized to an V αc_R T T 2 YZY VgV _ eYΔ aZ_ Wc d h Z εc_ eV UVgZV WFR_U eV device will then draw 3.7 μA from the supply typically.
VIN	8	Power supply input pin

Over operating free-air temperature range unless otherwise noted

PARAMETER	DEFINITION	MIN	MAX	UNIT
V _{IN}	Input voltage range	3.2	50	V
V _{CC}	VCC voltage range	3.2	6.1	V
T _J	Operating junction temperature	-40	125	°C

PARAMETER	DEFINITION	MIN	MAX	UNIT
V _{ESD}	Human Body Model(HBM), per ANSI-JEDEC-JS-001-2014 specification, all pins	-2	+2	kV
	Charged Device Model(CDM), per ANSI-JEDEC-JS-002-2014specification, all pins	-1	+1	kV

PARAMETER	THERMAL METRIC	MSOP-8	UNIT
R ₂	Junction to ambient thermal resistance ⁽¹⁾	132.8	°C/W
R _{4 (top)}	Junction to case (top) thermal resistance ⁽¹⁾	64.1	°C/W
R _B	Junction to board thermal resistance ⁽¹⁾	83.8	°C/W

(1) SCT provides R₂ and R₄ numbers only as reference to estimate junction temperatures of the devices. R₂ and R₄ are not a characteristic of package itself, but of many other system level characteristics such as the design and layout of the printed circuit board (PCB) on which the SCT81625Q is mounted, thermal pad size, and external environmental factors. The PCB board is a heat sink that is soldered to the leads and thermal pad of the SCT81625Q. Changing the design or configuration of the PCB board changes the efficiency of the heat sink and therefore the actual R₂ and R₄.

SCT81625Q

$V_{IN}=12V$, $T_J=-40^{\circ}C\sim 125^{\circ}C$, typical values are tested under $25^{\circ}C$.

SYMBOL	PARAMETER	TEST CONDITION	MIN	TYP	MAX	UNIT
Power Supply and Output						
V_{IN}	Operating input voltage		2.92		50	V
V_{IN_UVLO}	Input UVLO	V_{IN} rising		2.9		V
	Hysteresis			160		mV
I_{SD}	Shutdown current	$V_{FA/SYCN/SD}=5V$		3.7	8	uA
I_Q	Quiescent current from VIN	no load, no switching		460		uA
Reference and Control Loop						
V_{REF}	Reference voltage of FB	$T_J=25^{\circ}C$	1.241	1.26	1.278	V
		$T_J=-40\sim 125^{\circ}C$	1.222		1.297	
I_{FB}	FB pin leakage current	$V_{FB}=1V$			100	nA
G_{EA}	Error amplifier trans-conductance	$V_{COMP}=1.5V$	500	700	900	uS
I_{COMP_SRC}	Error amplifier maximum source current	$V_{FB}=V_{REF}-200mV$, $V_{COMP}=1.5V$	120	155	195	uA
I_{COMP_SNK}	Error amplifier maximum sink current	$V_{FB}=V_{REF}+200mV$, $V_{COMP}=1.5V$	-170	-130		

SYMBOL	PARAMETER	TEST CONDITION	MIN	TYP	MAX	UNIT
T _{SD} ⁽¹⁾	Thermal shutdown threshold	T _J rising		165		°C
	Hysteresis			25		°C

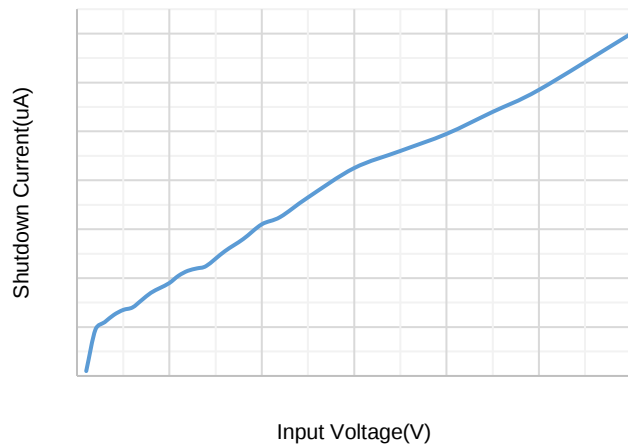


Figure 1. ISD vs Input Voltage

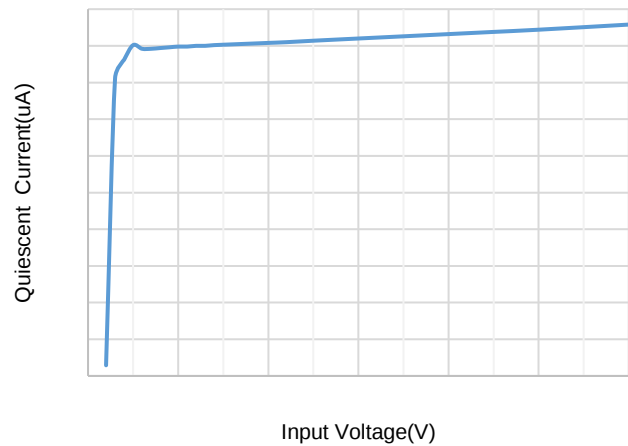


Figure 2. IQ vs Input Voltage

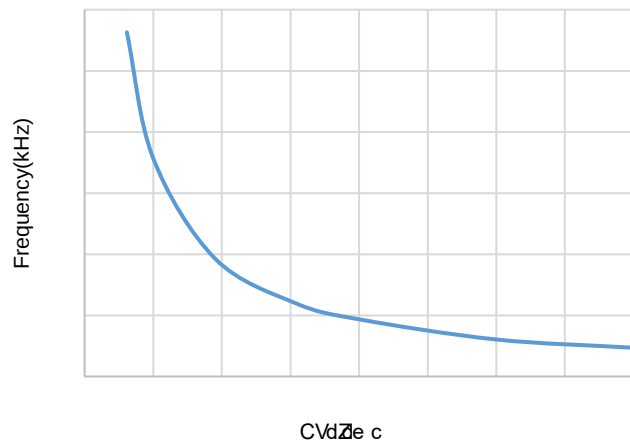


Figure 3. Switching Frequency vs RT

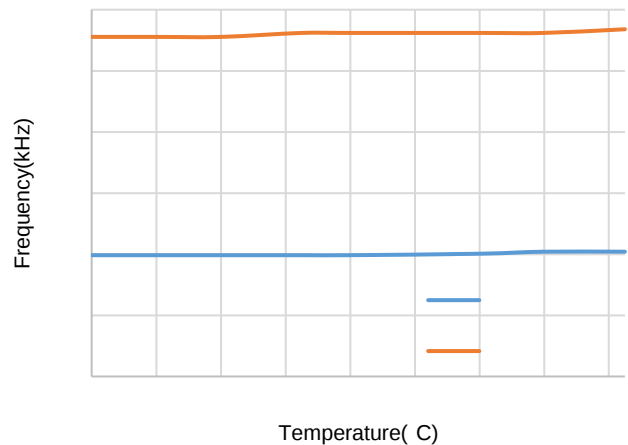


Figure 4. Switching Frequency vs Temperature

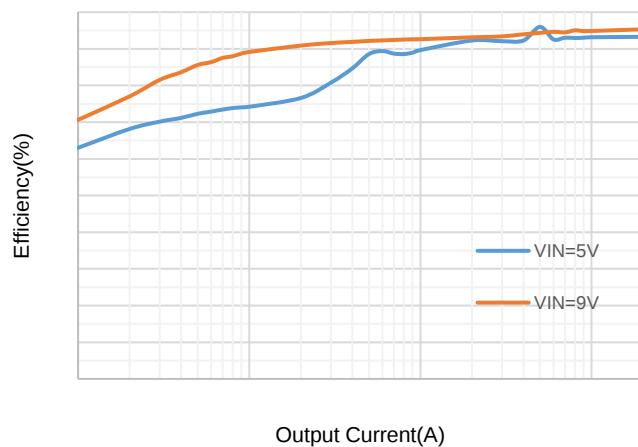


Figure 5. Efficiency vs Load Current, Boost, VOUT=12V

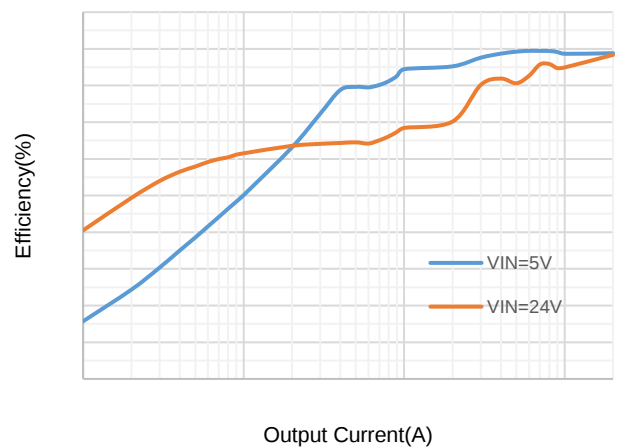


Figure 6. Efficiency vs Load Current, Sepsic, VOUT=12V

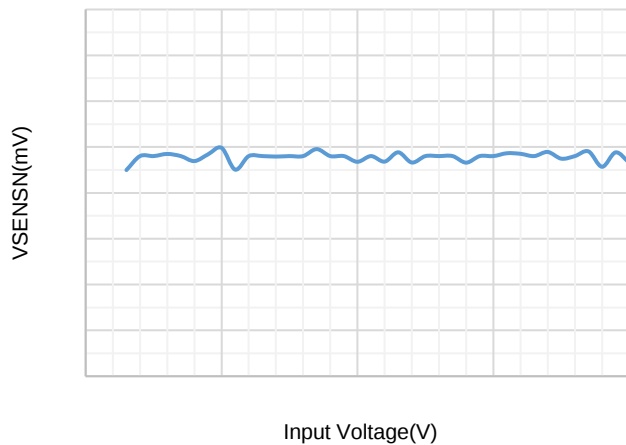


Figure 7. VSENSN vs Input Voltage

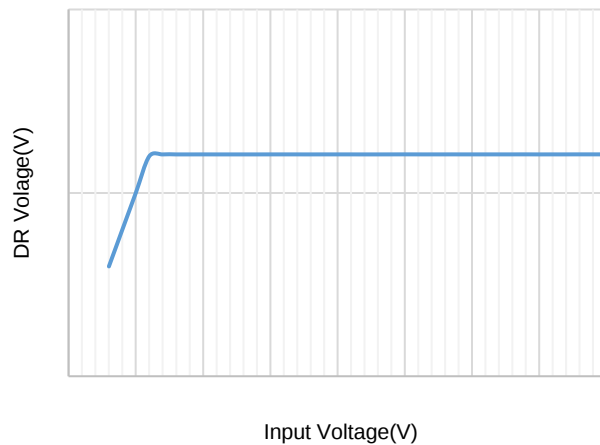


Figure 8. DR Voltage vs Input Voltage

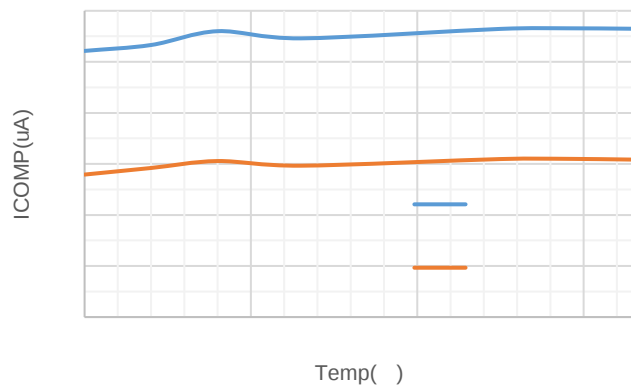


Figure 9. COMP Current vs Temperature

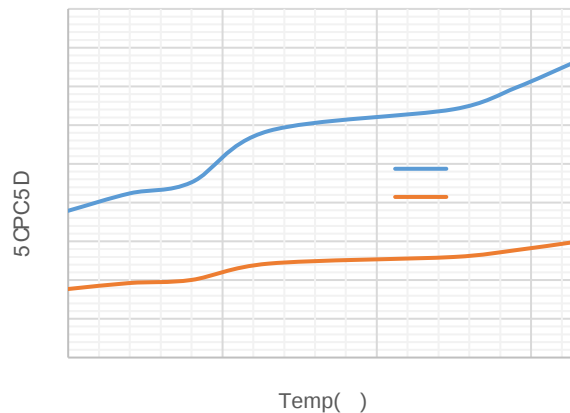


Figure 10. DR Resistance vs Temperature

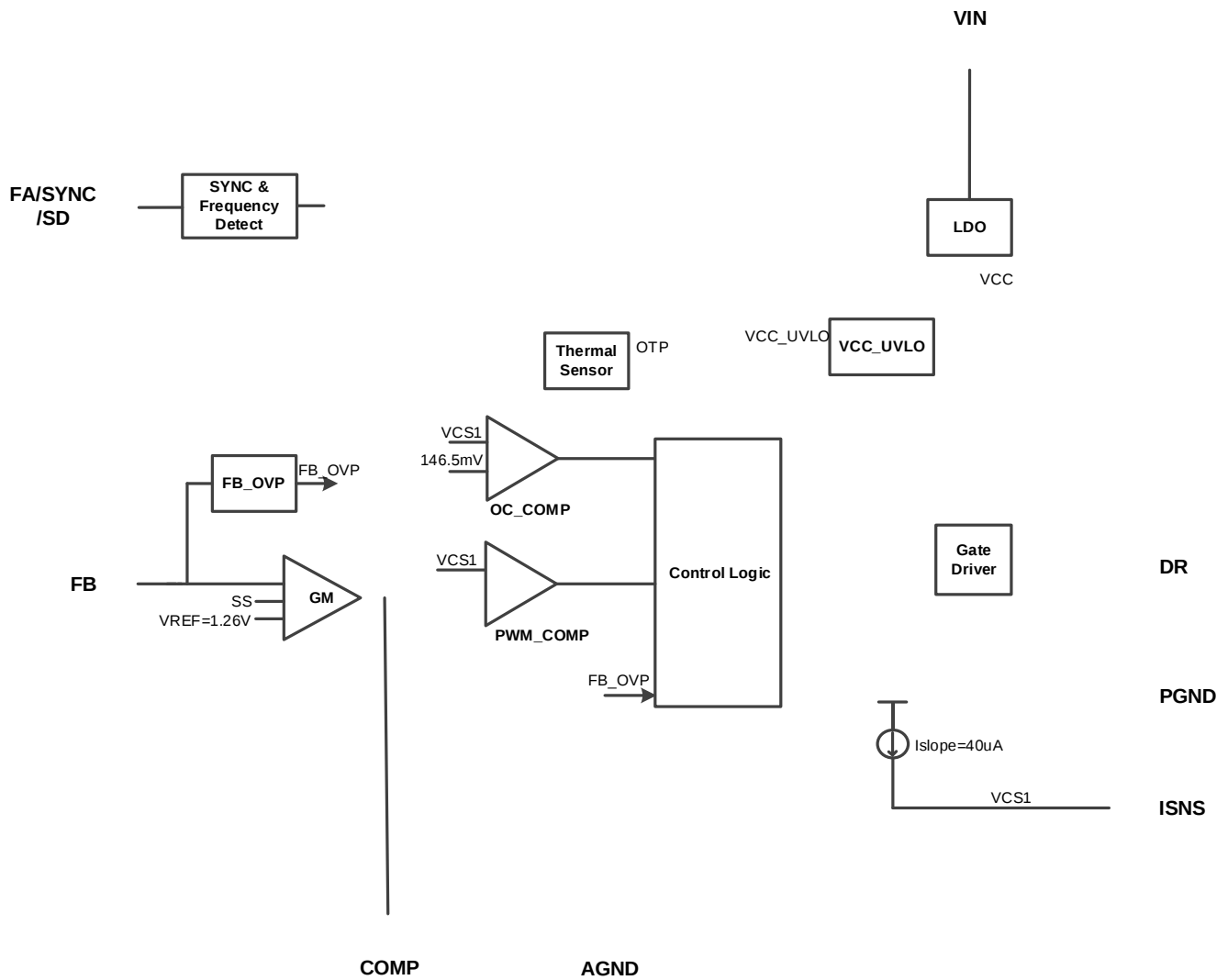


Figure 11. Functional Block Diagram

EYVTf α V_e UVT α dTYV VdR aVdeVZUFTe cTf α V_e := R_UT aRcVdeVdR aVUdZ_R GdR a e R Z α c_R j XV_VdR α U T α dZ_R GT EYV Tf α V_e dV_dV dVdZ α c CD6 Rd dY h_Z 7Zf dV T_gV α d eV dR aVUZUFTe cTf α V_e := e eVg dRXVdZ_R GdR a eVReZ ac a α Z_R e := df TYeVRe:

$$V_{smp} I_L * R_{SEN} \quad (1)$$

7Zf dV Zf d α ReV eV eV q h Yj Df S9Rc_Z dTZReZ_YRaaV_eV α ZXR_U V ZX d aVd > R_U > dVdaVTeZVj WdR a RcV Rd ac a α Z_R e eV ZUFTe cTf α V_e α ZXR_U V ZX d aVd > R_U > W dVdaVTeZVj H YVd > Z eV ZUFTe cd aVUf α ZXeV dh ZTY_eZ VR_U > W eV ZUFTe cd aVUf α ZXeV dh ZTY W eZ VR_URcV dVdUe > R_U > Sj :

$$M_1 M_{on} * R_{SEN} \quad (2)$$

$$M_2 M_{off} * R_{SEN} \quad (3)$$

7 ceVVS dee a Xj +

$$M_1 M_{on} * R_{SEN} Vin * R_{SEN} / L \quad (4)$$

$$M_2 M_{off} * R_{SEN} (Vout Vin) * R_{SEN} / L \quad (5)$$

:_7Zf dV Rd R ZTcRdVZ_eV RU Tf α V_e TRf dVd eVdR aVUdZ_R e ZTcRdV Sj GdR a EYV WTe W eV RU TYR_XV GdR a Re eVV_U V eV W d e h ZTYX TJ TV Z

$$'V_{smp1} \left(\frac{M_2}{M_1} \frac{M_c}{M_c} \right) * 'V_{smp0} \quad (6)$$

D H YV_ T aV_dReZ_dR a dZ_R dRUUJ h YZY > T d Vc eV_+

$$'V_{smp1} \left(\frac{M_2}{M_1} \right) * 'V_{smp0} \left(\frac{D}{1 D} \right) * 'V_{smp0} \quad (7)$$

H YV_5 / & GdR a hZ SV XcR α c eYR_ GdR a :_ eVc h dJd eV UZef cSR_TV d UZV α V_eD RgVj d R aV α cSR α Z_Z eV RUh Z TRf dV eV UZef cSR_TV e ZTcRdV

2WcRT aV_dReZ_dR a dRUUJ e eVT α dZ_R E V_df dV eV Re eV aV α cSVU dZ_R T_gV α Vd h V f de RZ α RZ_+

$$\left| \left(\frac{M_2}{M_1} \frac{M_c}{M_c} \right) \right| < 1 \quad (8)$$

EYVT aV_dReZ_dR a YRd SW_RUUJ Z α c_R j Z_eV D4E) ' &B EYVd aV W eV d T aV_dReZ_dR a YRd SW_dV VTeU e dReZ_W deRaa ZReZ_d R_U d gRf VUVaV_Ud_eV dh ZTYX Wbf V_Tj EY d aV TR_SV TR Tf ReU f dZ XeV Wc f R+

$$M_c V_{SL} * F_s \quad (9)$$

GD= d eV R a dUV W eV Z α c_R T aV_dReZ_dR a R_U 7D d eV T α Vcd dh ZTYX Wbf V_Tj

7 c dV W dZ d aVT aV_dReZ_TR_SV ZTcRdVU Sj RUJZX_V M eVc_R dVdZ α c CD= Z_eV:D6 d aReY 7Zf dV dY h d eV dV α a EYV M eVc_R j XV_VdR α U d aVT aV_dReZ_d eV RUUJ e eV Z α c_R d aV T aV_dReZ_V eV D4E) ' &B H YV_f dZX M eVc_R d aVT aV_dReZ_eV Wc f R Wc > T SVT Vd+

$$M_c (V_{SL} K * R_{SL}) * F_s \quad (10)$$

2 ej aZR gRf VWc VTe c < d % 2

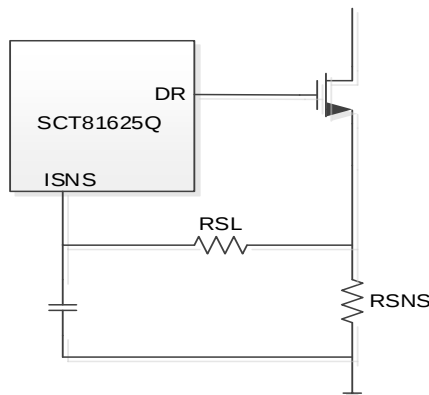


Figure13 .External RSL to increase slope compensation

Adjustable Peak Current Limit

The peak current limit is adjustable by connecting an external resistor R_{SL} to the $ISNS$ pin. The peak current limit I_{PEAK_CL} is determined by the following equation:

$$I_{PEAK_CL} = \frac{V_{SENSE}}{R_{SNS}} \cdot \frac{40\mu A \cdot R_{SL}}{D} \quad (11)$$

Where

- x V_{SENSE} is $ISEN$ pin limiting voltage (Typ.=146.5mV)
- x I_{PEAK_CL} is the inductor peak current limit
- x R_{SL} is Slope compensation resistor
- x D is Duty cycle
- x R_{SNS} is the Inductance peak current detection resistance

The output voltage is regulated by a feedback network consisting of a resistor divider R_{FBT} and R_{FBB} connected to the FB pin. The output voltage V_{OUT} is determined by the following equation:

The output voltage is regulated by a feedback network consisting of a resistor divider R_{FBT} and R_{FBB} connected to the FB pin. The output voltage V_{OUT} is determined by the following equation:

$$V_{OUT} = V_{REF} \cdot \left(1 + \frac{R_{FBT}}{R_{FBB}} \right) \quad (12)$$

where:

- x V_{REF} is the feedback reference voltage, typical 1.26V

Frequency Adjust/Shutdown/ Synchronization

The switching frequency f_{SW} is determined by the external capacitor C_{TJ} connected to the RT pin. The shutdown current I_{SD} is determined by the external resistor R_{SD} connected to the SD pin. The synchronization input $SYNC$ is used to synchronize the converter with an external clock source.

Typical Application (Boost)

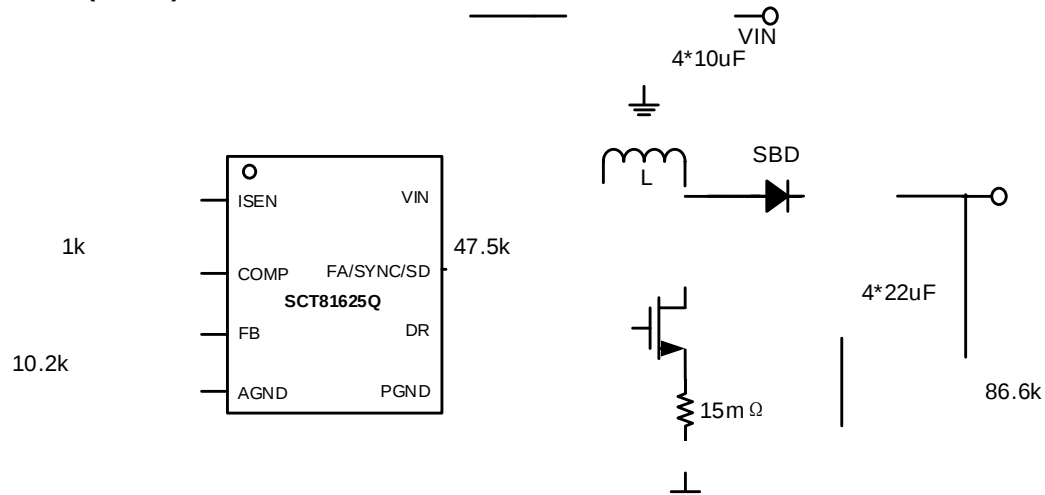


Figure 18. Application Schematic, 3V to 11V, 2A Boost Regulator at 400kHz

Design Parameters

Design Parameters	Example Value
Input Voltage	5V Normal 3V to 11V
Output Voltage	12V
Maximum Output Current	3A
Switching Frequency	400 KHz
Output voltage ripple (peak to peak)	75mV (Load=2A)

TY dV_Z_eYdR_XV W 7e % 7:VRgRfV h VceYR_ 7 d f dVU eYV_ac SV dh ZYZ aVUR_TV_Z_eVdTeZ_d
 c dh ZY_Z_X_ ZV TR_RVVTeYV D4E) ' &B E Z ac gV aVdVc R_TV VdaVTZ j h ZY GZ_SV h) g d Z d
 dT V_UUe f dVR Y dVdZe cReeYV_Zafee ac gZVR_C4 VdVc EYV dVdZe c d aRTVU_Z dVcZdh ZY eYV
 G: aZ h ZY_j RSj aRdd TRaRTZ cReYTYUe eYV G: aZ_UZVTej 2 7 c 7 TVdR Z TRaRTZ c d_VTVddRj
 Z_eYV_T_VZfReZ_EYV Sf_Zafe TRaRTZ cR_UZUf Te ch Z T__VTe_eYV eYVcdZV VdV dVdZe cReeYV_Zafe
 a h Vcdf aa j

Output Capacitor Selection

7 cd R faefeg dXVcZaV TY dVR h 6DC faefeTRaRTZ c ZVR TVdR Z TRaRTZ c EjaZR j ~% 7
 TVdR Z faefeTRaRTZ d h c Wc deRaa ZReZ_d 2 7 TVdR Z Sj aRdd TRaRTZ c d dT V_UUe SV
 aRTVURd T dVRd a ddZVe eYV dh ZY_UV 9ZYVc TRaRTZ cgRfVd TR_SVf dVUe Z ac gVeYV RUeR_dZ_e
 dVda_dV 5fV e R TRaRTZ cd UVReZ_Xf_UVc 54 SZd eYV SZd TR_dZ_ZR ej dUf TV TRaRTZ TV 4 VdR Z
 TRaRTZ d TR_dV de VdVZ TRaRTZ TV ReReUg dXV EYVdVdV VRgV RcXZ_eYVg dXV dReZ_Xe
 V_dV dVUVbfReV VVVTeYV TRaRTZ TV 7c eYV dVbfZU faefeg dXV cZaV f dV eYV VbfReZ_) R_U * e
 TRTf ReVeYV_ZZ f dVbfZU VVVTeYV TRaRTZ TV 4 FE

(18)

(19)

where

- x V_{ripple_c} is output voltage ripple caused by charging and discharging of the output capacitor.
- x V_{ripple_ESR} is output voltage ripple caused by ESR of the output capacitor.
- x V_{IN_MIN} is the minimum input voltage of boost converter.
- x V_{OUT} is the output voltage.
- x I_{OUT} is the output current.
- x I_{Lpeak} is the peak current of the inductor.
- x f_{sw} is the converter switching frequency.
- x ESR is the ESR resistance of the output capacitors.

Power MOSFET Selection

EYV W h ZX aRdR VdV dY f U SV dR V_Ze T_dZVRReZ_Wc > D76E+ eYV_dVdZdR_TV C5DP eYV
 ZZ f XReVeYVdY Ug dXV GE9P>: eYV eR XReV TYRcXV B X eYV dVgVdV eR_dVc TRaRTZ TV 4 CDD R_U
 eYV R Z f URZ_e d f cTVg dXV GBP>2l EYV aVR dh ZY_Z_Xg dXV SVh W_UdRZ_e d f cTV_Z_R 3 deZ
 XGV_Sj

$$V_{SW_PEAK} V_{IN} V_D \quad (20)$$

EYV_eYV GBP>2l Vd h Vc> D76E dY f U SV XdVdVceYR_eYV aVR dh ZY_Z_Xg dXV

EYV aVR dh ZY_Z_X Tf dV_eWh_ZXeYc f XY eYV > D76E d XGV_Sj +

$$I_{Q_PEAK} I_{LPEAK} \quad (21)$$

EYV C> D Tf dV_eYc f XY eYV > D76E d TR Tf ReU Sj +

$$I_{Q_RMS} \sqrt{(I_{LDC}^2 \frac{I_{LPP}}{12}) * D} \quad (22)$$

EYV_a h VcUdZReZ_Z > D76E TR_SV VdZ ReU Sj +

$$P_{DIS} I_{Q_RMS}^2 uR_{DS_ON} uD_{MAX} V_O V_{IN_MIN} I_{Q_PEAK} \frac{Q_g u f_{SW}}{I_G} \quad (23)$$

Where

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I_G is the gate drive current.

EWVe R a h VcUdzReZ _ W D76E ZTfUvd T _Uf TeZ _ dd Rd dY h _ Z eVWdeVc R_U dh ZYX dd Rd
dY h _ Z eVdVT _UeVc EWVe R a h VcUdzReZ _ dY f U SVh ZY aRT RXVeVc R cVdV V

Application Waveforms

Vin=5V, Vout=12V, unless otherwise noted

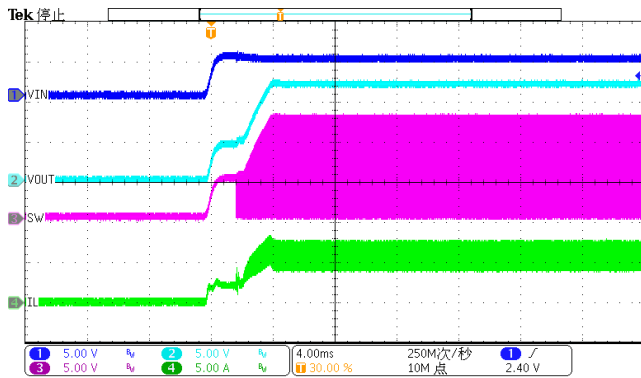


Figure 19. Power up(Iload=2A)

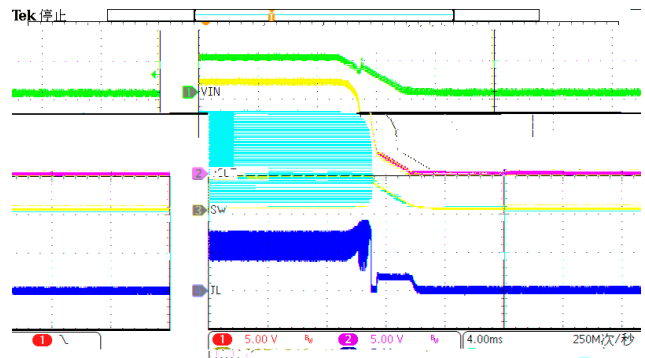


Figure 20. Power down(Iload=2A)

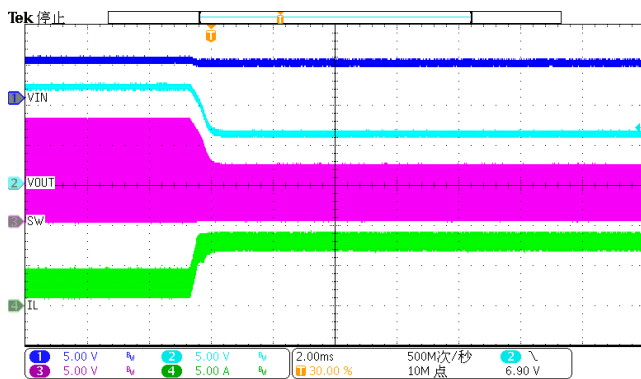


Figure 21. Over current protection (Iload=5A)

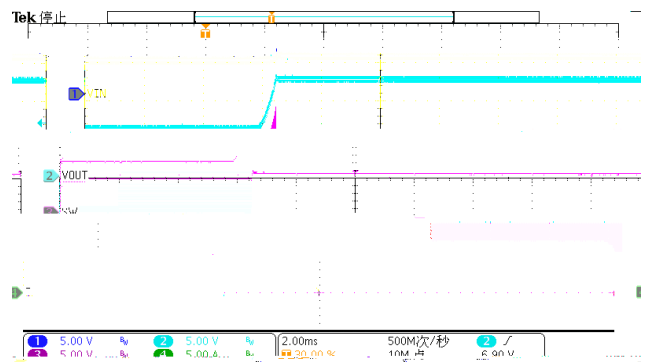


Figure 22. Over current recovery (Iload=5A)

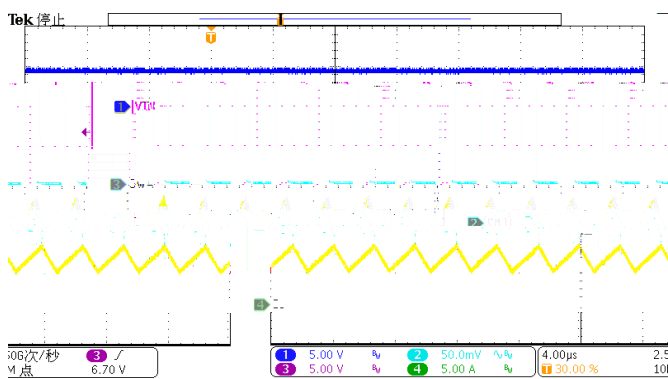


Figure 23. Steady-state (Iload=2A)

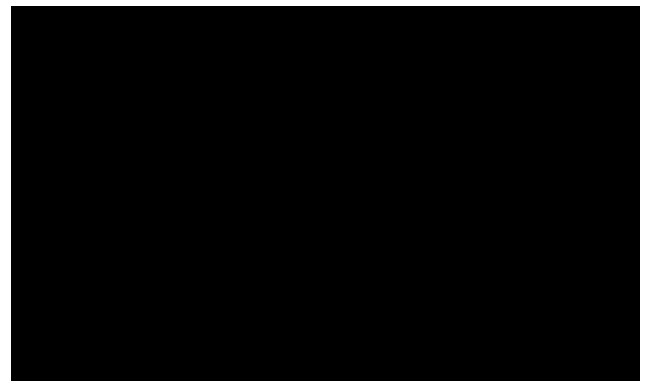


Figure 24. Sync Frequency

SCT81625Q

Typical Application (Sepic)

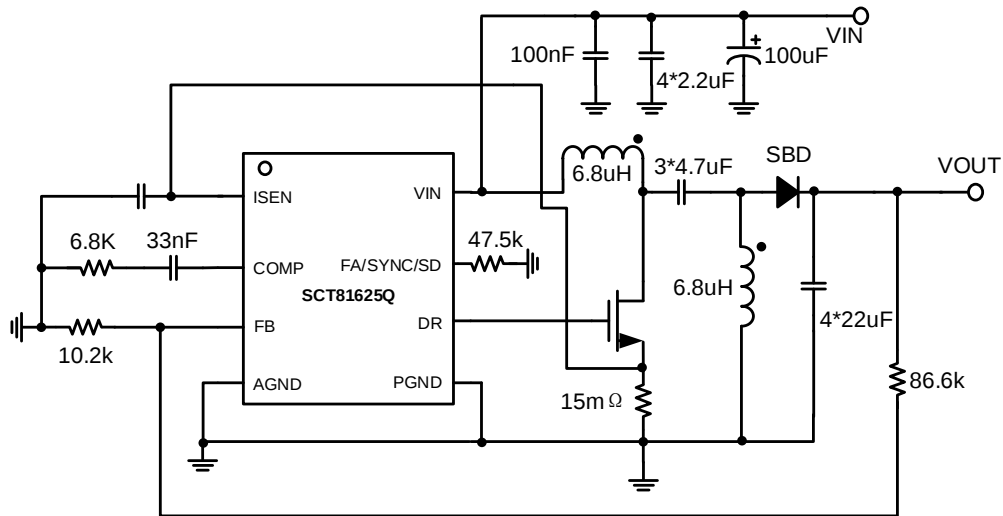


Figure 25. Application Schematic, 5V to 50V, 2A Sepic Regulator at 400kHz

Design Parameters

Design Parameters	Example Value
Input Voltage	24V Normal 5V to 50V
Output Voltage	12V
Maximum Output Current	2A
Switching Frequency	400 KHz
Output voltage ripple (peak to peak)	75mV (Load=2A)

Inductor Selection (Sepic)

2 X U d V Wc UVe/c Z_ZX eYV Z_Uf Td_TV e f dV Y _U V

EYVe R a h VcUdZReZ_ W D76E ZTfUd T_UfTeZ_ dd Rd dY h_Z eVWdeVc R_U dh ZYX dd Rd dY h_Z eVdVT_UaVc EYVe R a h VcUdZReZ_dY f U SVh ZY aRT RXVeVc R ReZXd

Output Diode Selection

EYVUZUVReeV f eafedZV f deh ZYdeR_UeV dVgVdVg RXVh YV_eV> D76E Z d c_WU _ EYVaVR dVgVdVg g RXV Z XZV_Sj +

$$V_{D_PEAK} \quad V_{IN_MAX} \quad V_{O_MAX} \quad (35)$$

EYVUZUVdY f URd SVTRaRSVe Wh dh ZYVaVR Tf aV_e:BPA62<

EYVa h VcUdZReZ_ W eVUZUV Z Vb f R e eVWh RdUg RXVUc a f eZ d f eaf eTf aV_e DTY e j UZUVd Rd dT V_UUJ YVdVe Z Z ZVeVa h Vc dd

Coupling Capacitor Selection

7 cTVR Z TRaRTZ d h ZY h 6DC eYVaVR e aVR g RXV Za V _T f a Z X TRaRTZ c Z VdeZ ReU Sj +

$$V_{CS}' \quad \frac{I_O \omega D_{MAX}}{C_S \omega f_{SW}} \quad (36)$$

EYV R Z f g RXVRTc dd eV T f a Z X TRaRTZ c Z R Z f Zafeg RXV EYVg RXV ReZ X W eV T f a Z X TRaRTZ c f deSV XaVc eYR_Z

EYVC>D Tf aV_e W f a Z X TRaRTZ c Z XZV_Sj +

$$I_{CS_RMS} \quad I_O \quad \sqrt{\frac{V_O - V_D}{V_{IN_MIN}}} \quad (37)$$

EYV Z R R cV C>D Tf aV_e eYc f XY T f a Z X TRaRTZ c dV ReZVe f eaf e a h Vc 6_df dV eV T f a Z X TRaRTZ c TR_h ZYdeR_U Zh ZYX U YVReXV_VReZ_e YRgVac aVceVc R aVdVc R_TV

Input Capacitor Selection

EYVD6A:4 YRdR_ZUf Te cReZafedZV eYf d eV Zaf eTf aV_e Z T _eZ f f d R_U c Z Xf Rc EYVC>D Tf aV_e Wh Z X eYc f XY eV Zaf e TRaRTZ c Z XZV_Sj +

$$I_{IN_RMS} \quad \frac{I_{L1}}{\sqrt{12}} \quad (38)$$

DZTV Zaf eTf aV_e cZa V Z dV ReZV h eV TRaRTZ TVh f U SV _ee T c Z R H YZV 7 Z e R c Y X Vc gR f V Z d c _Xj dT V_UUJ Z dVce ac gZV d eRSV Zaf edf aa j

Output Capacitor Selection

DZ ZRce S deT_gV aVc eYVD6A:4 f eaf e TRaRTZ cdf W d R cV Tf aV_e cZa V EYV TRaRTZ TV f deSV V _f XY e ac gZV eV RU Tf aV_e EYV R Z f g RXV Za V Z_eV f eaf e TRaRTZ c Z +

$$V_{OUT}' \quad \frac{I_O \omega D_{MAX}}{C_{OUT} \omega f_{SW}} \quad ESR \quad u \quad I_{L1_PEAK} \quad I_{L2_PEAK} \quad (39)$$

2ddf Z_XTVR Z TRaRTZ d RdV f dWU YVdR_U 6DC TR_SV X_ dU eV f eaf e TRaRTZ c Z XZV_Sj +

$$C_{OUT} \quad t \quad \frac{I_O \omega D_{MAX}}{V_{OUT}' f_{SW}} \quad (40)$$

EYV f eaf e TRaRTZ c f deYRgVRV_f XY C>D Tf aV_e ReZ_Xe YR_UV eV R Z f C>D Tf aV_e Z_eV f eaf e TRaRTZ c TR Tf ReU Sj +

$$I_{COUT_RMS} = I_O \sqrt{\frac{D_{MAX}}{1 + D_{MAX}}} \quad (41)$$

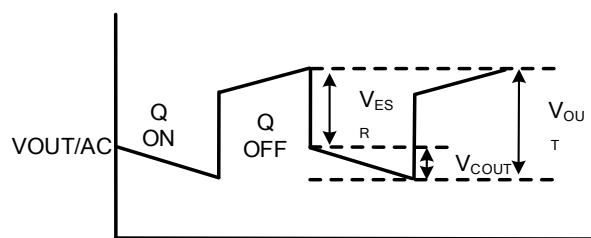


Figure 26. Output Voltage Ripple

